

PRE-RELEASE VERSION (FDIS)



Field Device Integration (FDI) – Part 6: FDI Technology Mapping

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 25.040.40; 35.100.05

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FINAL DRAFT INTERNATIONAL STANDARD (FDIS)

PROJECT NUMBER:

IEC 62769-6 ED2

DATE OF CIRCULATION:

2020-11-06

CLOSING DATE FOR VOTING:

2020-12-18

SUPERSEDES DOCUMENTS:

65E/593/CDV, 65E/643/RVC

IEC SC 65E : DEVICES AND INTEGRATION IN ENTERPRISE SYSTEMS

SECRETARIAT:

United States of America

SECRETARY:

Mr Donald (Bob) Lattimer

OF INTEREST TO THE FOLLOWING COMMITTEES:

HORIZONTAL STANDARD:

FUNCTIONS CONCERNED:

EMC

ENVIRONMENT

QUALITY ASSURANCE

SAFETY

SUBMITTED FOR CENELEC PARALLEL VOTING

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TITLE:

Field Device Integration (FDI) - Part 6: FDI Technology Mapping

PROPOSED STABILITY DATE: 2023

NOTE FROM TC/SC OFFICERS:

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 6: Technology Mapping

FOREWORD

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International Standard IEC 62769 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) redesign of the security concept for UIP execution.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
XX/XX/FDIS	XX/XX/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

FIELD DEVICE INTEGRATION (FDI) –

Part 6: Technology Mapping

1 Scope

This part of IEC 62769 specifies the technology mapping for the concepts described in the Field Device Integration (FDI) standard. The technology mapping focuses on implementation regarding the components FDI Client and User Interface Plug-in (UIP) that are specific only to the WORKSTATION platform/.NET as defined in IEC 62769-4.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62769-1, *Field Device Integration (FDI) – Part 1: Overview*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

IEC 62541 (all parts), *OPC Unified Architecture*

ISO/IEC 19505-1, *Information technology – Object Management Group Unified Modeling Language (OMG UML) – Part 1: Infrastructure*

ISO/IEC 29500, (all parts) *Information technology – Document description and processing languages – Office Open XML File Formats*